

MOS FIELD EFFECT TRANSISTOR 2SK3793

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

The 2SK3793 is N-channel MOS Field Effect Transistor designed for high current switching applications.

ORDERING INFORMATION

PART NUMBER	PACKAGE
2SK3793	Isolated TO-220

FEATURES

• Super low on-state resistance

 $R_{DS(on)1} = 125 \text{ m}\Omega \text{ MAX.} \text{ (VGS} = 10 \text{ V, ID} = 6 \text{ A)}$

 $R_{DS(on)2}$ = 148 m Ω MAX. (Vgs = 4.5 V, ID = 6 A)

- Low Ciss: Ciss = 900 pF TYP.
- Built-in gate protection diode

(Isolated TO-220)



ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (Ves = 0 V)	VDSS	100	V
Gate to Source Voltage (V _{DS} = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	I _{D(DC)}	±12	Α
Drain Current (pulse) Note1	D(pulse)	±22	Α
Total Power Dissipation (Tc = 25°C)	P _{T1}	20	W
Total Power Dissipation (T _A = 25°C)	P _{T2}	2.0	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	-55 to +150	°C
Single Avalanche Current Note2	las	10	Α
Single Avalanche Energy Note2	Eas	10	mJ

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

2. Starting Tch = 25°C, VDD = 50 V, RG = 25 Ω , VGS = 20 \rightarrow 0 V

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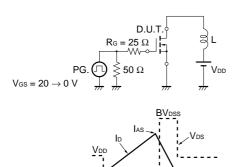


ELECTRICAL CHARACTERISTICS (TA = 25°C)

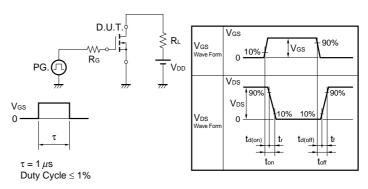
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 100 V, V _{GS} = 0 V			10	μΑ
Gate Leakage Current	Igss	V _{GS} = ±20 V, V _{DS} = 0 V			±10	μΑ
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	1.5	2.0	2.5	V
Forward Transfer Admittance Note	yfs	V _{DS} = 10 V, I _D = 6 A	5.0	10.3		S
Drain to Source On-state Resistance Note	RDS(on)1	V _{GS} = 10 V, I _D = 6 A		89	125	mΩ
	RDS(on)2	V _{GS} = 4.5 V, I _D = 6 A		96	148	mΩ
Input Capacitance	Ciss	V _{DS} = 10 V		900		pF
Output Capacitance	Coss	V _{GS} = 0 V		110		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		50		pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = 50 V, I _D = 6 A		9		ns
Rise Time	t r	V _{GS} = 10 V		5		ns
Turn-off Delay Time	t _{d(off)}	$R_G = 0 \Omega$		30		ns
Fall Time	tf			4		ns
Total Gate Charge	Q _G	V _{DD} = 80 V		21		nC
Gate to Source Charge	Qgs	V _{GS} = 10 V		3.0		nC
Gate to Drain Charge	Q _{GD}	I _D = 12 A		6.2		nC
Body Diode Forward Voltage Note	V _{F(S-D)}	I _F = 12 A, V _{GS} = 0 V		0.89	1.5	V
Reverse Recovery Time	trr	I _F = 12 A, V _{GS} = 0 V		52		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		94		nC

Note Pulsed

TEST CIRCUIT 1 AVALANCHE CAPABILITY



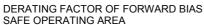
TEST CIRCUIT 2 SWITCHING TIME

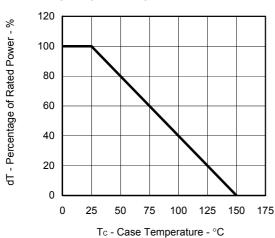


TEST CIRCUIT 3 GATE CHARGE

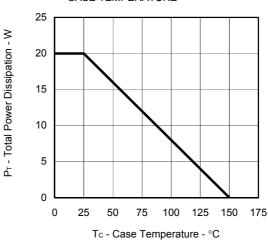
-Starting Tch

TYPICAL CHARACTERISTICS (TA = 25°C)

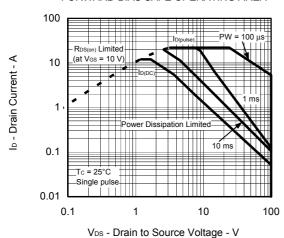




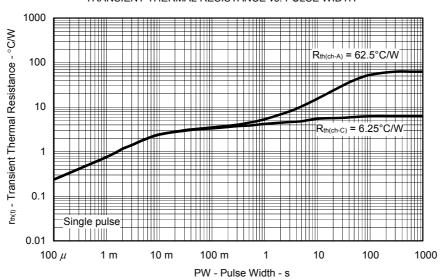
TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



FORWARD BIAS SAFE OPERATING AREA

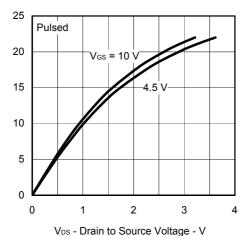


TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

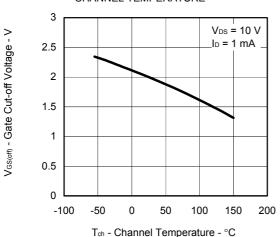


Ip - Drain Current - A

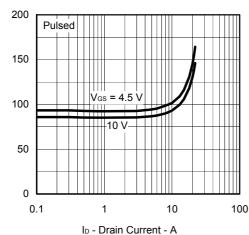
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



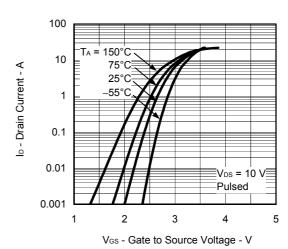
GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



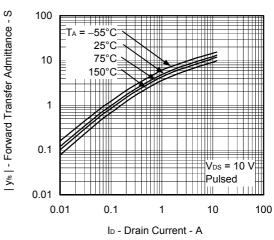
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



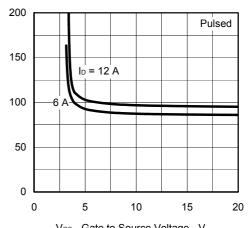
FORWARD TRANSFER CHARACTERISTICS



FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

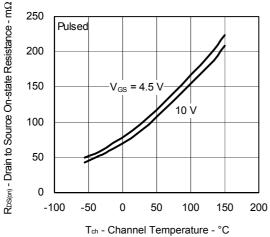


Vgs - Gate to Source Voltage - V

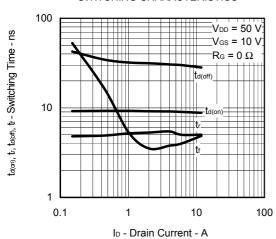
RDS(m) - Drain to Source On-state Resistance - m\Omega

R_{DS(ση)} - Drain to Source On-state Resistance - mΩ

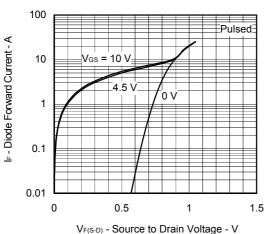
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



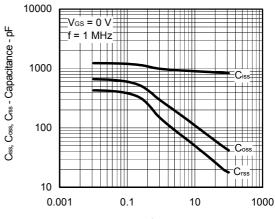
SWITCHING CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE

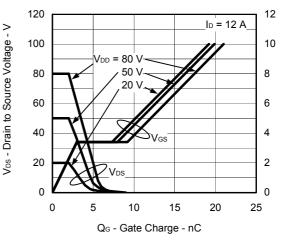


CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

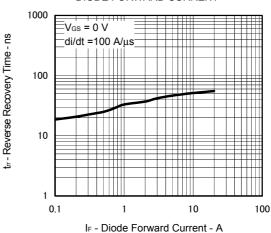


V_{DS} - Drain to Source Voltage - V

DYNAMIC INPUT/OUTPUT CHARACTERISTICS

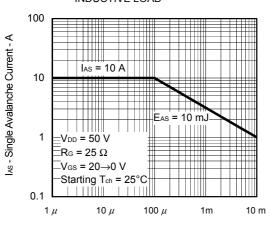


REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT



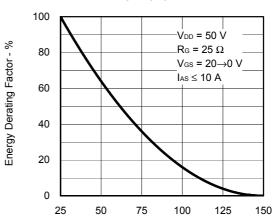
Vos - Gate to Source Voltage - V

SINGLE AVALANCHE CURRENT vs. INDUCTIVE LOAD



L - Inductive Load - H

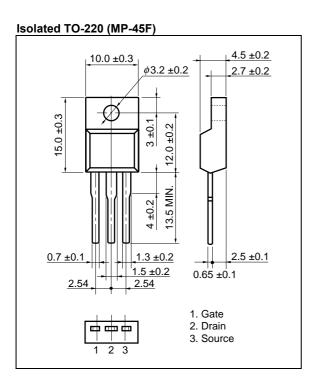
SINGLE AVALANCHE ENERGY DERATING FACTOR



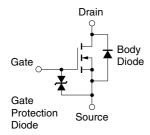
Starting T_{ch} - Starting Channel Temperature - $^{\circ}$ C



PACKAGE DRAWING (Unit: mm)



EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD.

When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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